



PK950 (v1.0) January24, 2018

100% Material Declaration Data Sheet for Spartan-7 CSGA225

Average Weight : 0.4710 g

Component	Substance Description	CAS # or Description	% of component	Use in product	Component weight / substance weight (in grams)	Component % of total
Silicon die					0.011504	2.442%
	Silicon	7440-21-3	100.00		0.011504	
Die Attach Material					0.003027	0.643%
	Silver	7440-22-4	74.00		0.002240	
	Bismaleimide monomer	trade secret	15.00		0.000454	
	Methacrylate resin	trade secret	7.50		0.000227	
	Additive	trade secret	3.00		0.000091	
	Proprietary	trade secret	0.50		0.000015	
Mold Compound					0.224209	47.603%
	Epoxy Resin	Trade secret	7.50		0.016816	
	Phenol Resin A	9003-35-4	3.00		0.006726	
	Phenol Resin B	Trade secret	3.00		0.006726	
	Silica(Amorphous) A	60676-86-0	67.95		0.152350	
	Silica(Amorphous) B	7631-86-9	15.00		0.033631	
	Metal Hydroxide	Trade secret	3.00		0.006726	
	Carbon black	1333-86-4	0.55		0.001233	
Copper Wire					0.003139	0.666%
	Copper	7440-50-8	98.08		0.003079	
	Palladium	7440-05-3	1.80		0.000057	
	Gold	7440-57-5	0.12		0.000004	
Solder Ball					0.055691	11.824%
	Tin	7440-31-5	96.50		0.053742	
	Silver	7440-22-4	3.00		0.001671	
	Copper	7440-50-8	0.50		0.000278	
Substrate					0.173430	36.822%
	Gold	7440-57-5	2.63		0.004561	
	Nickel	7440-02-0	18.68		0.032397	
	Copper Foil	7440-50-8	3.81		0.006608	
	Copper plating	7440-50-8	30.02		0.052064	
	Continuous Filament Fiber Glass	65997-17-3	11.11		0.019268	
	BT Core	Trade secret	14.39		0.024957	
	Prepreg	Trade secret	9.47		0.016424	
	Solder mask	Trade secret	9.89		0.017152	

Revision History

Date	Version	Description of Revisions
1/24/2018	1.0	Initial Xilinx release.